

瀚纳瑞化工(上海)有限公司 上海市奉贤区目华路111号 邮编:201507

HANAREY CSE9788-H Product Data Sheet

Apr 2025

Hanarey CSE9788-H is a light and moisture-curable reworkable conformal coating. Its key advantage lies in providing longterm protection for circuit boards against dust and corrosion, while also delivering excellent moisture resistance and chemical durability. This is a one-component material that requires no mixing before use. It can be cured using various types of UV lamps and is compatible with multiple spray coating processes. Its ability to UV cure tack free in seconds enables faster processing, greater output, and lower processing costs. This product is in full compliance with RoHS 2.0 directive 2015/863/EU.

UNCURED PROPERTIES *

Property	Value	Test Method
Chemical Class	Acrylated Urethane	N/A
Appearance	Transparent Yellowish	N/A
Density, g/ml	1.10	ASTM D1875
Viscosity, cP	400~850	HSTM 751#
Shelf Life from Date of Manufacture	180 Days	N/A

CURED MECHANICAL PROPERTIES * *

Property	Value	Test Method	
Hardness	D40~D70 °	ASTM D2240	
	D79	ASTM D2240	
Tensile at Break, MPa	10.15	ASTM D638	
Elongation at Break, %	2.65	ASTM D638	
Modulus of Elasticity, MPa	570	ASTM D638	
CTEα1, μm/m/°C	112	ASTM E831	
CTEα2, μm/m/°C	200	ASTM E831	

Not Specifications

N/A

Not Applicable
Measured after UV cure followed by 10 days at 25°C/75% RH

Ω Measured after UV cure only

Cured by Dymax 5000-EC (all spectrum), 120 mW/cm2 intensity, 30 s

HSTM refers to Hanarey Standard Testing Method

OTHER CURED PROPERTIES **

Property	Value	Test Method
Boiling Water Absorption, % (2 h)	0.65	ASTM D570
Water Absorption, % (25°C, 24 h)	0.17	ASTM D570
Linear Shrinkage, %	1.95	ASTM D2566
Glass Transition Tg, *C	74	ASTM D5418

ELECTRICAL PROPERTIES * ¥

Property	Value	Test Method
Dielectric Constant (1 MHz)	2.8069	ASTM D150
Dissipation (1 MHz)	0.0186	ASTM D150
Dielectric Breakdown Voltage, kV/mm	58.85	HSTM D149 [‡]
Volume Resistivity, ohm-cm	7.3*10 ¹⁵	ASTM D257
Surface Resistivity, ohm	8.12*10 ¹⁴	ASTM D257

ADHESION *¥

Substrate	Shear Strength/ Cross-Cut	
PC / PCB	8.3 MPa #	
PCB	5B	

CLEAN UP

Uncured Hanarey materials may be removed from dispensing components and parts with non-alcoholic solvents. Cured material will be impervious to many solvents and difficult to remove. Cleanup of cured material may require mechanical methods such as ultrasonic bath, water, jet, vacuum tweezers, air knife and/or warming to aid in the removal.

TRANSPORTATION, STORAGE, AND SHELF LIFE

Do not crush and throw to avoid leakage during transportation. It is verified that the product is exposed to ambient temperature for a short time during transportation will not affect the product performance.

Store the material in a low-humidity, cool, and dark place when not in use. This product may polymerize upon prolonged exposure to ambient and artificial light as well as moisture. This material shelf life noted on page 1 of this document, when stored between 10°C (50°F) and 32°C (90°F) in the original, unopened container.

Resealing large containers under dry inert gas, such as nitrogen, can help maintain the shelf life. Smaller syringes and cartridges should be kept in moisture barrier bags with desiccant when not in use.



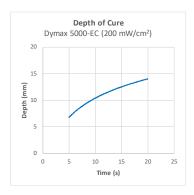
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CURING GUIDELINES

First Step: light cure

The graph below shows the increase in depth of cure as a function of exposure time at Dymax 5000-EC 200 mW/cm². These depths are only due to light cure.



Second Step: > 7 days moisture cure

Full cure is best determined empirically by curing at different times and intensities and measuring the corresponding change in cured properties such as tackiness, adhesion, hardness, etc. Full cure is defined as the point at which more energy exposure no longer improves cured properties. Higher intensities or longer cures (up to 5x) generally will not degrade Hanarey light-curable adhesives.

Hanarey recommends that customers employ a safety factor by curing longer and/or at higher intensities than required for a full cure. Although Hanarey Application Engineering can provide technical support and assist with process development, each customer ultimately must determine and qualify the appropriate curing parameters required for their unique application.

GENERAL INFORMATION

This product is intended for industrial use only. Keep out of the reach of children. Avoid breathing vapors. Avoid contact with skin, eyes, and clothing. Wear impervious gloves. Repeated or continuous skin contact with uncured material may cause irritation. Remove material from the skin with soap and water. Never use organic solvents to remove material from the skin and eyes. For more information on the safe handling of this material, please refer to the Safety Data Sheet before use.

The data provided in this document are based on historical testing that Hanarey performed under laboratory conditions as they existed at that time and are for informational purposes only. The data are neither specifications nor guarantees of future performance in a particular application. Hanarey does not guarantee that this product's properties are suitable for the user's intended purpose. The contents of this document are subject to change. Unless specifically agreed to in writing, Hanarey shall have no obligation to notify the user about any change to its content.

Data Collected: Mar 2025 Date of Revision: 8 Apr 2025